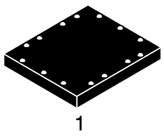
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

14 PIN FLIP−CHIP
CASE 499AQ−01
ISSUE O

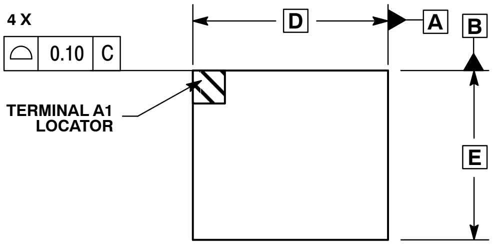
DATE 17 JUN 2005

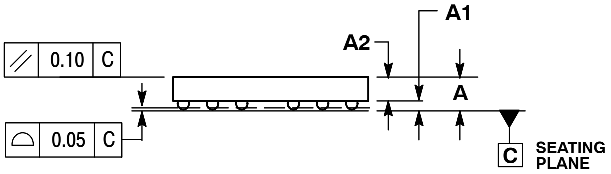


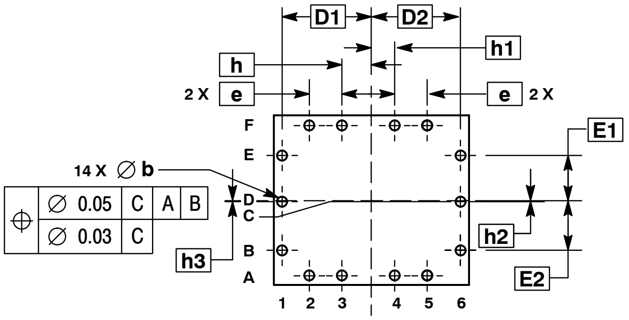
SCALE 3:1

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	---	0.692	0.742
A1	0.142	0.167	0.192
A2	0.500	0.525	0.550
b	0.190	0.220	0.224
D	4.300 BSC		
D1	1.983 BSC		
D2	1.949 BSC		
E	3.730 BSC		
E1	1.016 BSC		
E2	1.075 BSC		
e	0.716 BSC		
h	0.648 BSC		
h1	0.514 BSC		
h2	0.034 BSC		
h3	0.029 BSC		







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DESCRIPTION:	14 PIN FLIP−CHIP, SCV6904, 4.3 X 3.73 MM	PAGE 1 OF 1

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